REMARKS

35 U.S.C. § 102 Rejections

The Examiner has rejected claims 23, 25-28, and 30 under 35 U.S.C. § 102(b) as being anticipated by Weld.

Claim 23 has been amended to include the dimensions of the magnetic material particles being approximately one micron by two microns by ten microns. Specifically, claim 23 includes the limitation "wherein the dimensions of the magnetic material particles are approximately one micron by two microns by ten microns."

Weld discloses a package comprising a molded encapsulated electronic component including a lead frame substrate, wherein the component is coupled to the substrate through an elastomeric, anisotropic, and electrically conductive interconnect comprising a polymer and conductive particles of cobalt or iron. These electrically conductive particles or flakes may be mixed with the uncured polymer and the mixture is subjected to a magnetic field as the polymer is cured. Weld makes no mention of the specific shapes or dimensions of the conductive particles. Specifically, Weld does not disclose the dimensions of the magnetic material particles being approximately one micron by two microns by ten microns.

Therefore, claim 23 is not anticipated by Weld because claims 23 includes a limitation that is not disclosed in Weld.

Claims 25-28 and 30 are dependent on claim 23 and should be allowable for the same reasons stated above.

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Applicant, accordingly, respectfully requests withdrawal of the rejections of claims 23, 25-28 and 30 under 35 U.S.C. § 102(b) as being anticipated by Weld.

The Examiner has rejected claims 23-28 and 30 under 35 U.S.C. § 102(e) or 102(a) as being anticipated by <u>Jiang</u>.

Claim 23 has been amended to include the dimensions of the magnetic material particles being approximately one micron by two microns by ten microns. Specifically, claim 23 includes the limitation, "wherein the dimensions of the magnetic material particles are approximately one micron by two microns by ten microns."

<u>Jiang</u> does not disclose the dimensions of the magnetic material particles being approximately one micron by two microns by ten microns. <u>Jiang</u> discloses conductive interconnections that are formed by depositing an adhesive material, made up of ferromagnetic particles dispersed within a matrix material, on a semiconductor substrate, such as an electronic component (Abstract). The first electronic component 102 and the second electronic component 124 are pressed together such that a plurality of ferromagnetic particles 114 of each adhesive material column 120 contact the first electronic component bond pads 104 and the second electronic component bond pads 126 to make a predetermined degree of electrical connection therebetween (column 6, lines 13-20). <u>Jiang</u> makes no mention of the specific dimensions or shapes of the ferromagnetic particles 114. Specifically,

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<u>Jiang</u> does not disclose the dimensions of the magnetic material particles being approximately one micron by two microns by ten microns.

Therefore, claim 23 is not anticipated by <u>Jiang</u> because claim 23 includes a limitation that is not disclosed in <u>Jiang</u>.

Claims 24-28 and 30 are dependent on claim 23 and should be allowable for the same reasons as claim 23 stated above.

Applicant, accordingly, respectfully requests withdrawal of the rejections of the claims 23-28 and 30 under 35 U.S.C. § 102(e) or 102(a) as being anticipated by Jiang.

35 U.S.C. § 103 Rejections

The Examiner has rejected claims 23-30 under 35 U.S.C. § 103(a) as being unpatentable over <u>Weld</u> and further in view of either <u>Litwin</u> or <u>Appelt</u>.

Claim 23 has been amended to include the dimensions of the magnetic material particles being approximately one micron by two microns by ten microns. Specifically, claims 23 includes the limitation, "wherein the dimensions of the magnetic material particles are approximately one micron by two microns by ten microns."

As previously discussed, <u>Weld</u> does not teach or suggest the dimensions of the magnetic material particles being approximately one micron by two microns by ten microns.

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Neither <u>Litwin</u> nor <u>Appelt</u> teach or suggest the dimensions of the magnetic material particles being approximately one micron by two microns by ten microns.

Therefore, claim 23 is patentable over <u>Weld</u> and further in view of either <u>Litwin</u> or <u>Appelt</u> because claim 23 includes the limitation that is not taught or suggested by <u>Weld</u>, <u>Litwin</u>, and <u>Appelt</u>.

Claims 24-30 are dependents on claim 23 and should be allowable for the same reasons as claim 23 stated above.

Applicant, accordingly, respectfully requests withdrawal of the rejections of claims 23-30 under 35 U.S.C. § 103(a) as being unpatentable over <u>Weld</u> and further in view of either <u>Litwin</u> or <u>Appelt</u>.

The Examiner has rejected claims 23- 30 under 35 U.S.C. § 103(a) as being unpatentable over <u>Jiang</u> in view of <u>Litwin</u>.

Claim 1 has been amended to include the dimensions of the magnetic material particles being approximately one micron by two microns by ten microns. Specifically, claim 23 includes the limitation, "wherein the dimensions of the magnetic material particles are approximately one micron by two microns by ten microns."

As previously discussed neither <u>Jiang</u> nor <u>Litwin</u> teach or suggest the dimensions of the magnetic material particles being approximately one micron by two microns by ten microns.

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Therefore, claim 23 is patentable over <u>Jiang</u> in view of <u>Litwin</u> because claim 23 includes a limitation that is not taught or suggested by <u>Jiang</u> and <u>Litwin</u>.

Claims 24-30 are dependent on claim 23 and should be allowable for the same reasons as claim 23 stated above.

Applicant, accordingly, respectfully requests withdrawal of the rejections of claims 23-30 under 35 U.S.C. § 103(a) as being unpatentable over <u>Jiang</u> in view of <u>Litwin</u>.

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Applicant respectfully submits that the present application is in condition for allowance. If the Examiner believes a telephone conference would expedite or assist in the allowance of the present application, the Examiner is invited to call Mark A. Kupanoff at (408) 720-8300.

Pursuant to 37 C.F.R. 1.136(a)(3), applicant(s) hereby request and authorize the U.S. Patent and Trademark Office to (1) treat any concurrent or future reply that requires a petition for extension of time as incorporating a petition for extension of time for the appropriate length of time and (2) charge all required fees, including extension of time fees and fees under 37 C.F.R. 1.16 and 1.17, to Deposit Account No. 02-2666.

Respectfully submitted,

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